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Schmenger et al.(10) **Pub. No.: US 2023/0230894 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **POWER MODULE****H05K 7/20** (2006.01)**H01L 23/32** (2006.01)(71) Applicant: **Siemens Aktiengesellschaft**, München
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A power module includes a heat sink, a power unit formed at least partially inside the heat sink and/or on the heat sink and comprising a semiconductor element and a substrate, and a device designed to enclose the power unit and to center a control unit with respect to the power unit. The device includes a frame designed to surround the substrate at least partially, a first projecting section designed to engage in a recess or an opening of the heat sink, and a second projecting section designed to engage in a recess or an opening or a notch of the control unit and to have an outline which when viewed in cross-section is at least essentially star-shaped with at least a first leg, a second leg and a third leg.

